



Semiconductor Device Type: C5X 008 TSSOP 4.4mm Matte Tin			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials			J-STD-609A Product Marking and/or Pkg. Labeling e3	
Basic Substance	CAS Number	Contained In Sub-Component	% Total Weight	mg/part	ppm	19.49	(mg) Total	Mold Compound	% of Total Weight	59.06
Silica, vitreous	60676-86-0	Mold Compound	50.201	16.566	502.010		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	3.617	1.194	36.174		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin	Trade Secret	Mold Compound	3.617	1.194	36.174		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.447	0.478	14.470		Epoxy, Cresol Novolac	29690-82-2	2.45	
Carbon Black	1333-86-4	Mold Compound	0.177	0.058	1.772		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	30.020	9.907	300.200		Total			100.00
Nickel	7440-02-0	Lead Frame	0.801	0.264	8.006	10.40	(mg) Total	Lead Frame	% of Total Weight	31.52
Silver	7440-22-4	Lead Frame	0.526	0.174	5.261		Copper	7440-50-8	95.24	
Silicon	7440-21-3	Lead Frame	0.142	0.047	1.418		Nickel	7440-02-0	2.54	
Magnesium	7439-95-4	Lead Frame	0.032	0.010	315		Silver	7440-22-4	1.67	
Silver	7440-22-4	Die Attach	1.008	0.333	10,080		Silicon	7440-21-3	0.45	
2,6-Diglycidyl phenyl allyl ether	EINECS (417-470-1)	Die Attach	0.056	0.018	560		Magnesium	7439-95-4	0.10	
Epoxy Resin	9003-36-5	Die Attach	0.056	0.018	560		Total			100.00
Silicon	7440-21-3	Chip (Die)	6.300	2.079	63,000	0.37	(mg) Total	Die Attach	% of Total Weight	1.12
Copper	7440-50-8	Wire Bond Copper palladium coated (CuPd)	0.177	0.058	1,769		Silver	7440-22-4	90.00	
Palladium	7440-05-3	Wire Bond Copper palladium coated (CuPd)	0.003	0.001	32		2,6-Diglycidyl phenyl allyl ether	EINECS (417-470-1)	5.00	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.820	0.601	18,200		Epoxy Resin	9003-36-5	5.00	
TOTALS:			100.000	33.000	1,000,000		Total			100.00
0.0330 g Total Mass										
						2.08	Total (mg)	Chip (Die)	% of Total Weight	6.30
							Doped Silicon	7440-21-3	100.00	
						Total			100.00	
						0.06	(mg) Total	Wire Bond Copper palladium coated (CuPd)	% of Total Weight	0.18
							Copper	7440-50-8	98.25	
							Palladium	7440-05-3	1.75	
						Total			100.00	
						0.60	(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	1.82
							Tin	7440-31-5	100.00	
						Total			100.00	
						33.000				100.00

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at <http://ul.com/global/eng/pages/offering/industries/chemicals/plastics/>

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at <http://echa.europa.eu/web/guest/candidate-list-table>